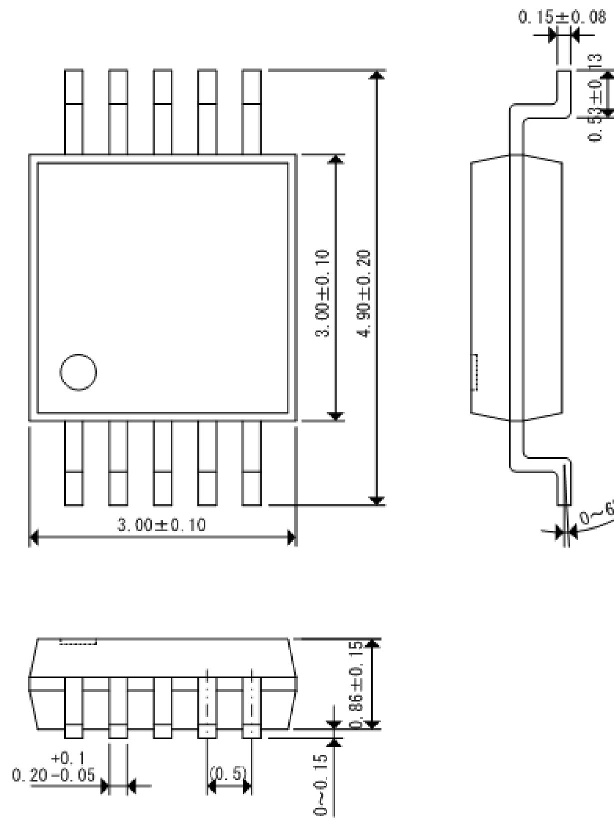
Packaging Information / Reference Pattern Layout Dimensions

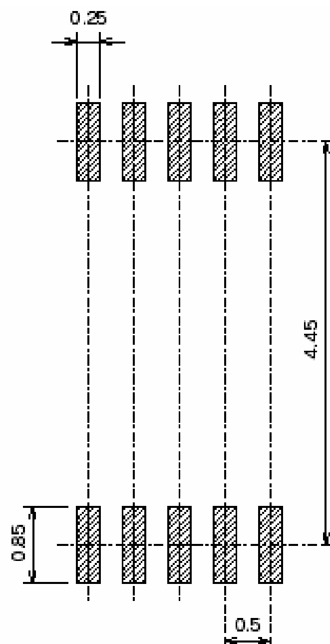
●MSOP-10

Unit: mm

■Packaging Information



■Reference Pattern Layout Dimensions

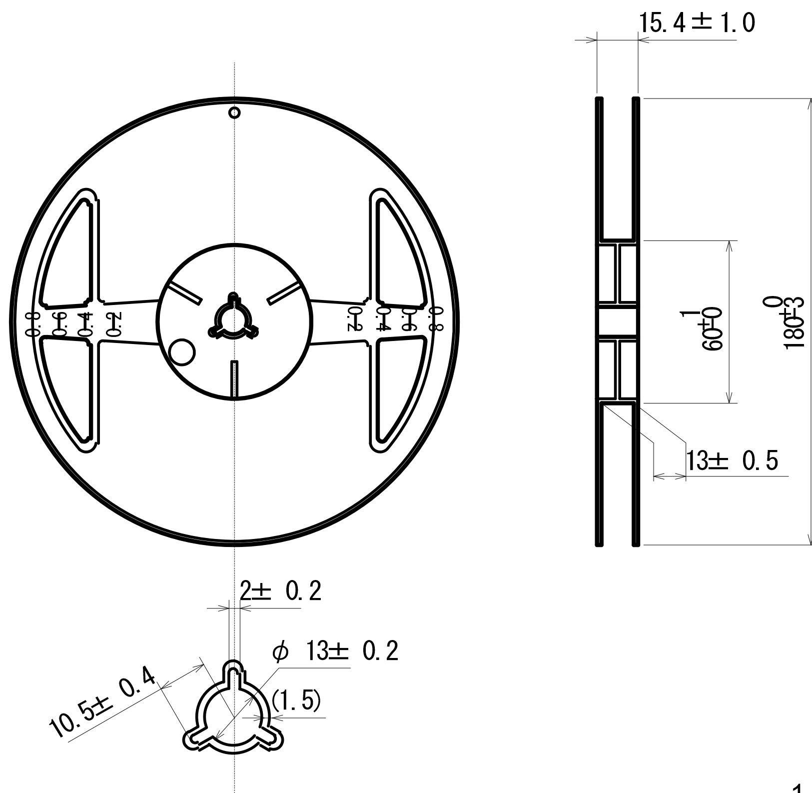


テーピング仕様 / Taping Specifications

MSOP-10

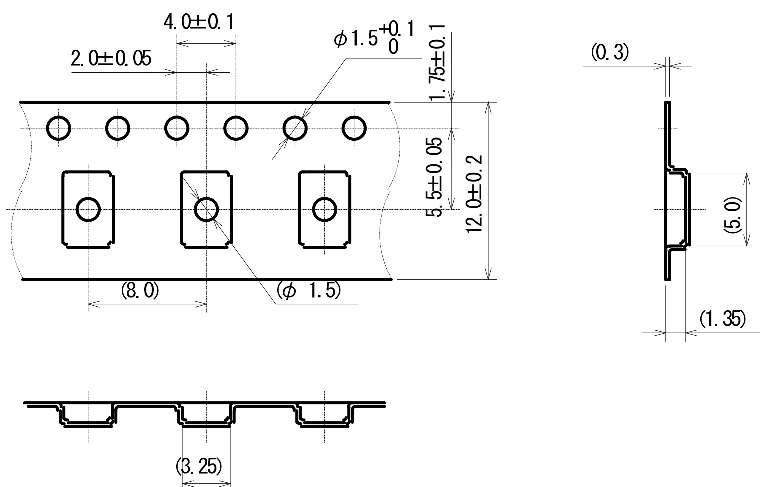
Unit: mm

●リール/Reel

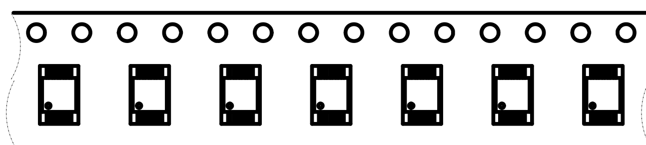


1,000pcs/reel

●テーピング仕様/Taping Specifications



direction of feed



R Type :[Device orientation : Right]

Standard feed

●MSOP-10 Power Dissipation

Power dissipation data for the MSOP-10 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition : Mount on a board

Ambient : Natural convection

Soldering : Lead (Pb) free

Board : Dimensions 40mm×40mm（1600mm^2 in one side）

1st Inner Metal Layer about 50% tied to the pin 10

2nd Inner Metal Layer does not exist

3rd Inner Metal Layer does not exist

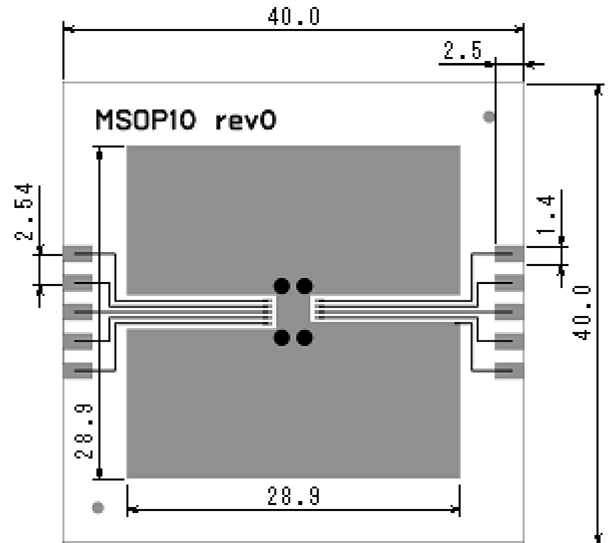
4th Inner Metal Layer about 50% tied to the pin 10

Each pin is tied to the copper traces

Material : Glass Epoxy（FR-4）

Thickness : 1.6mm

Through-hole : 10 x 0.8 Diameter

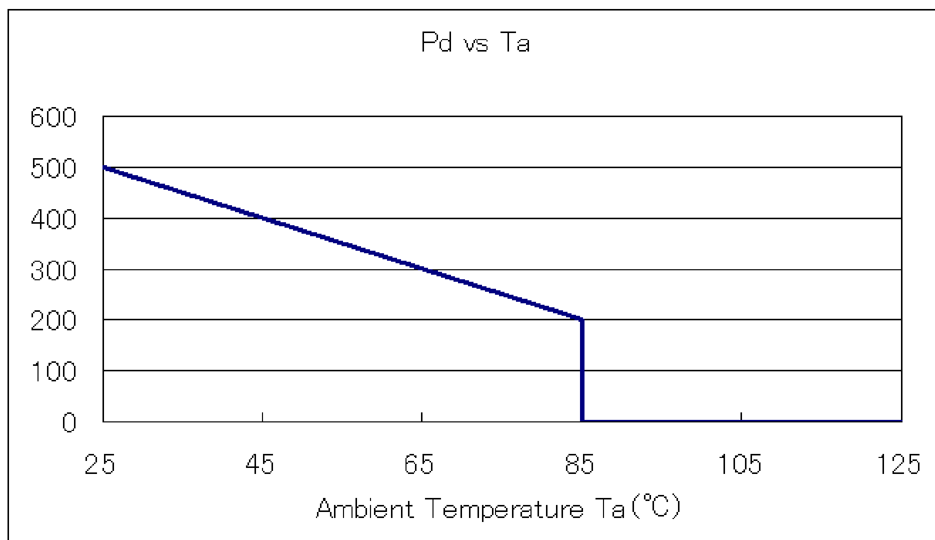


Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient temperature

Board Mount (Tjmax=125℃)

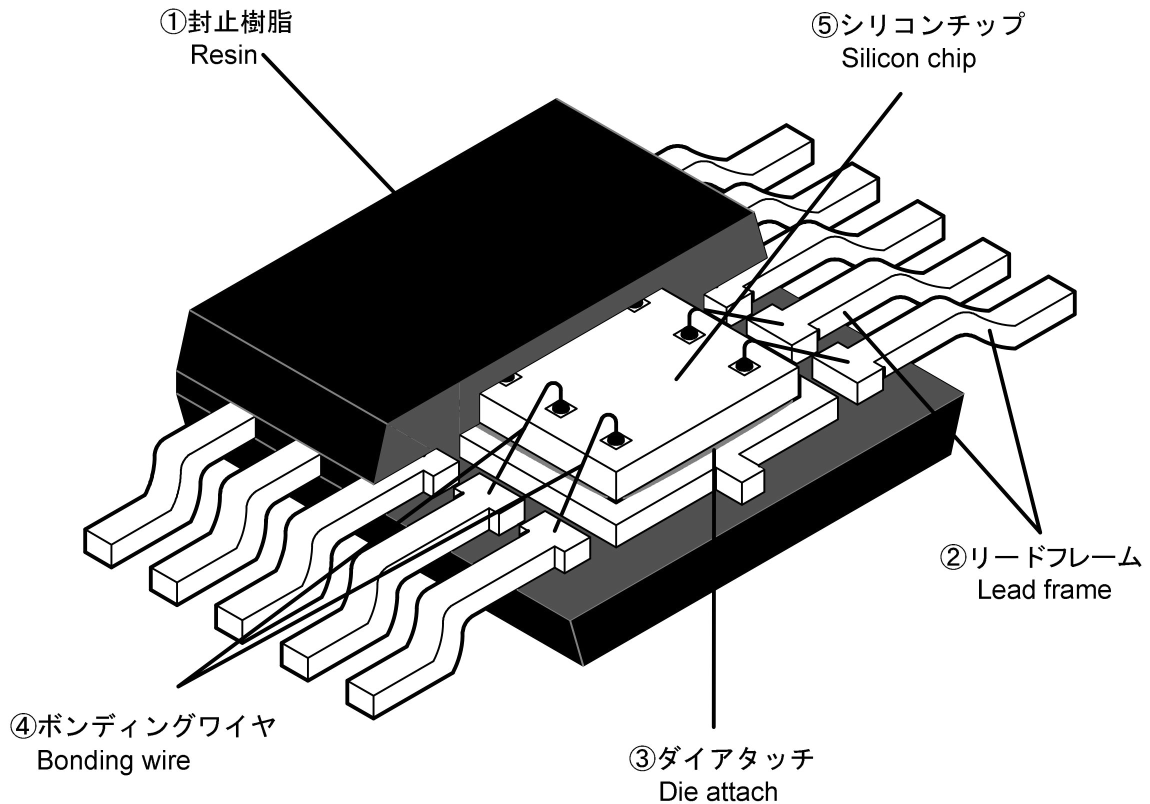
Ambient Temperature (℃)	Power Dissipation Pd (mW)	Thermal Resistance (℃/W)
25	500	200.00
85	200	



MSOP-10構造図
MSOP-10 Perspective

TOREX

RoHS対応品
RoHS Compliance



	項 目 Item	材 料 Material	備 考 Note
①	封止樹脂 Resin	エポキシ樹脂 Epoxy resin	難燃グレード/Flammability rating UL94V-0
②	リードフレーム Lead frame	銅系 Copper alloy	
	端子処理 Lead plating	鉛フリーはんだメッキ Lead(Pb) free solder plating	
③	ダイアタッチ Die attach	エポキシ Epoxy	
④	ボンディングワイヤ Bonding wire	Au	
⑤	シリコンチップ Silicon chip	Si	

捺印表示 Marking	レーザー Laser marking